

CLAIMS:

1. (Previously presented) A polishing composition comprising:
  - a) an abrasive;
  - b) a fluoride salt; and
  - c) an acetylenic alcohol;wherein the acetylenic alcohol has at least two hydroxyl substituents.
2. (Cancelled)
3. (Previously presented) The polishing composition of Claim 1 wherein the acetylenic alcohol is 2,4,7,9-tetramethyl-5-decyn-4,7-diol.
4. (Previously presented) The polishing composition of Claim 1 wherein the acetylenic alcohol is a C<sub>4</sub>-C<sub>22</sub> alkyne.
5. (Previously presented) The polishing composition of Claim 4 wherein the acetylenic alcohol is a C<sub>12</sub>-C<sub>16</sub> alkyne.
6. (Previously presented) The polishing composition of Claim 1 wherein the abrasive is a colloidal abrasive.
7. (Previously presented) The polishing composition of Claim 6 wherein the colloidal abrasive is colloidal silica.

8. (Previously presented) The polishing composition of Claim 1 wherein the fluoride salt is ammonium fluoride.

9. (Previously presented) A method for chemical mechanical planarization of a substrate comprised of dielectric material, the method comprising the steps of:

- i. providing a substrate comprised of dielectric material in contact with a polishing pad;
- ii. providing a composition for chemical mechanical planarization comprising a) an abrasive; b) a fluoride salt; and c) an acetylenic alcohol; and
- iii. polishing the substrate with the composition to effect at least partial planarization of the substrate;

wherein the acetylenic alcohol of the composition has at least two hydroxyl substituents.

10. (Cancelled)

11. (Previously presented) The method of Claim 9 wherein the acetylenic alcohol of the composition is 2,4,7,9-tetramethyl-5-decyn-4,7-diol.

12. (Previously presented) The method of Claim 9 wherein the acetylenic alcohol of the composition is a C<sub>4</sub>-C<sub>22</sub> alkyne.

13. (Previously presented) The method of Claim 12 wherein the acetylenic alcohol of the composition is a C<sub>12</sub>-C<sub>16</sub> alkyne.

14. (Previously presented) The method of Claim 9 wherein the abrasive of the composition is a colloidal abrasive.

15. (Previously presented) The method of Claim 14 wherein the colloidal abrasive is colloidal silica.

16. (Previously presented) The method of Claim 9 wherein the fluoride salt of the composition is ammonium fluoride.

17. (Previously presented) A polishing composition comprising:

- a) an abrasive;
- b) a fluoride salt selected from the group consisting of ammonium fluoride, sodium fluoride, and potassium fluoride; and
- c) an acetylenic alcohol;

wherein the acetylenic alcohol has at least two hydroxyl substituents.

18. (Previously presented) A polishing composition comprising:

- a) an abrasive;
- b) ammonium fluoride; and
- c) 2,4,7,9-tetramethyl-5-decyn-4,7-diol.